Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

# 2SK3131

# Chopper Regulator DC-DC Converter and Motor Drive Applications

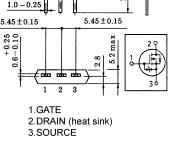
• Fast reverse recovery time  $t_{rr} = 105 \text{ ns (typ.)}$ 

• Built-in high-speed free-wheeling diode

• Low drain—source ON resistance : RDS (ON) =  $0.085 \Omega$  (typ.) • High forward transfer admittance :  $|Y_{fs}| = 35 S$  (typ.) • Low leakage current :  $I_{DSS} = 100 \mu A$  (max) ( $V_{DS} = 500 V$ ) • Enhancement mode :  $V_{th} = 2.4 \sim 3.4 V$  ( $V_{DS} = 10 V$ ,  $I_{D} = 1 mA$ )

#### **Absolute Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	500	V
Drain-gate voltage (Re	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	500	V
Gate-source voltage		V <sub>GSS</sub>	±30	V
DC Drain current	DC (Note 1)	$I_{D}$	50	Α
DC Drain current	Pulse (Note 1)	I <sub>DP</sub>	200	Α
Drain power dissipatio	n (Tc = 25°C)	P <sub>D</sub>	250	W
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	525	mJ
Avalanche current		I <sub>AR</sub>	50	Α
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	25	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C



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Weight: 9.75 g (typ.)

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Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.5	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	35.7	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 357  $\mu$ H,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 50 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device.

Please handle with caution.

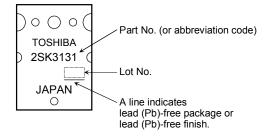
## **Electrical Characteristics (Ta = 25°C)**

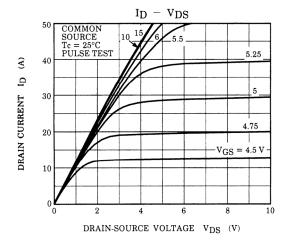
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±100 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	_	V
Gate threshold v	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.4	_	3.4	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A	_	0.085	0.11	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 25 A	15	35	_	S
Input capacitano	e	C <sub>iss</sub>			11000	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	2100	_	
Output capacitance		C <sub>oss</sub>		_	4200	_	
Switching time	Rise time	tr	$V_{\rm GS}$ $V_{\rm GS}$ $V_{\rm OV}$ $V_{\rm DD}$ $V_{\rm DD}$ $V_{\rm DD}$	_	105	_	
	Turn-on time	t <sub>on</sub>		_	160	ı	ns
	Fall time	t <sub>f</sub>		_	65	ı	115
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	_	245	_	
Total gate charge (Gate-source plus gate-drain)		Qg			280		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		150		nC
Gate-drain ("miller") charge		$Q_{gd}$			130	_	

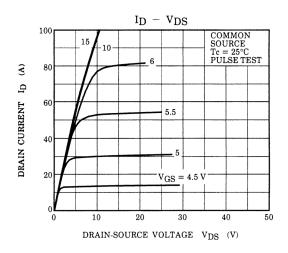
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

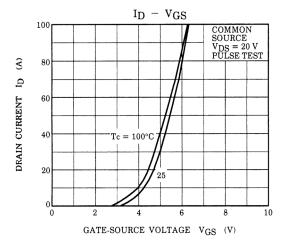
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	50	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	200	Α
Forward voltage (diode)	V <sub>DSF</sub>	V <sub>DR</sub> = 25 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 50 A, V <sub>GS</sub> = 0 V		105	_	ns
Reverse recovery charge	Qrr	dl <sub>DR</sub> / dt = 100 Å / μs		380	_	nC

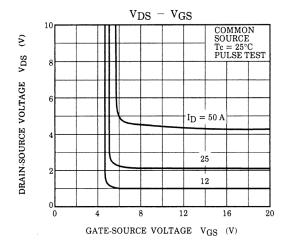
### Marking

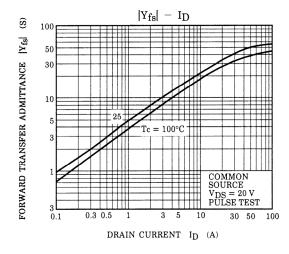


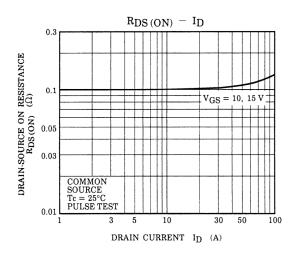


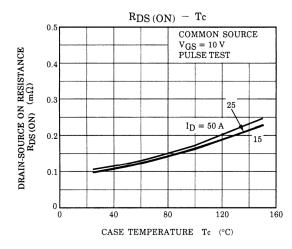


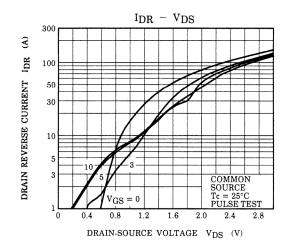


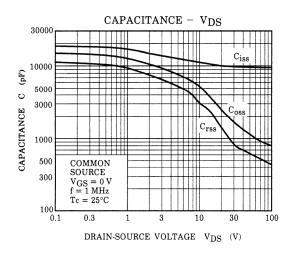


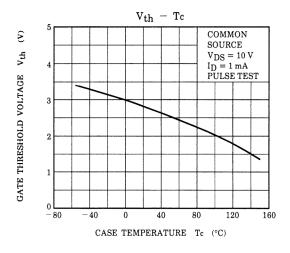


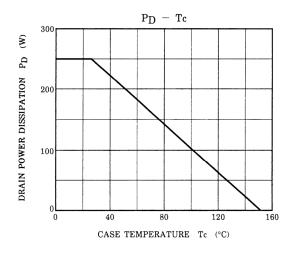


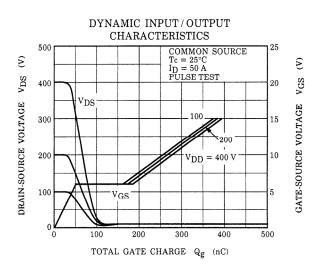




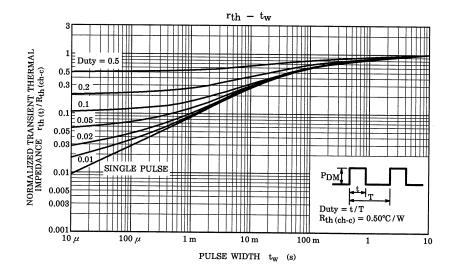


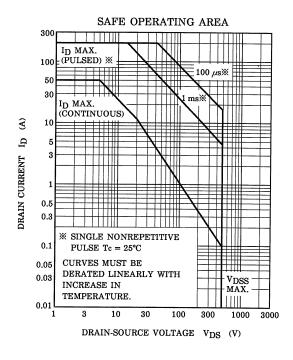


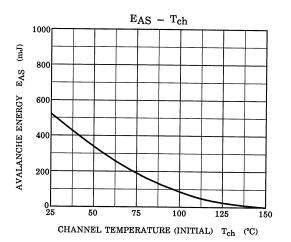


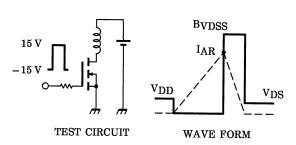


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$$\begin{split} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 357~\mu H \end{split}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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